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ABSOLUTE MAXIMUM RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Average forward current		I_F	20	mA
Reverse input voltage		V_R	5	V
Enable input voltage		V_E	$V_{CC} + 0.5 V$	V
Enable input current		I_E	5	mA
Surge current	$t = 100 \mu s$	I_{FSM}	200	mA
Input junction temperature		$T_{J \max.}$	125	°C
Output power dissipation		P_{diss}	35	mW
OUTPUT				
Supply voltage	1 min maximum	V_{CC}	7	V
Output current		I_O	50	mA
Output voltage		V_O	7	V
Output junction temperature		$T_{J \max.}$	125	°C
Output power dissipation		P_{diss}	85	mW
COUPLER				
Isolation voltage	$t = 1 \text{ min}$	V_{ISO}	5300	V_{RMS}
Storage temperature		T_{stg}	-55 to +150	°C
Operating temperature		T_{amb}	-40 to +100	°C
Lead solder temperature	for 10 s		260	°C
Solder reflow temperature ⁽¹⁾			260	°C

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.
- ⁽¹⁾ Refer to reflow profile for soldering conditions for surface mounted devices (SMDW). Refer to wave profile for soldering conditions for through hole devices (DIPW).

RECOMMENDED OPERATING CONDITIONS					
PARAMETER	TEST CONDITION	SYMBOL	MIN.	MAX.	UNIT
Operating temperature		T_{amb}	-40	100	°C
Supply voltage		V_{CC}	4.5	5.5	V
Input current low level		I_{FL}	0	250	μA
Input current high level		I_{FH}	5	15	mA
Logic high enable voltage		V_{EH}	2	V_{CC}	V
Logic low enable voltage		V_{EL}	0	0.8	V
Output pull up resistor		R_L	330	4K	Ω
Fanout	$R_L = 1 \text{ k}\Omega$	N		5	-

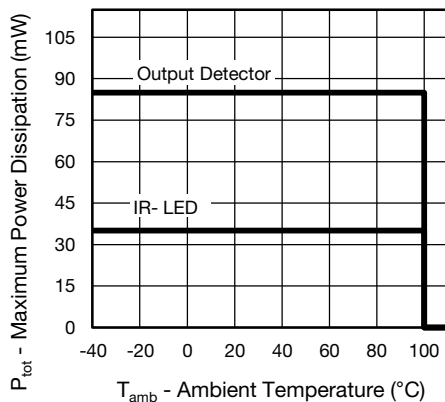


Fig. 1 - Dissipated Power vs. Ambient Temperature



ELECTRICAL CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Input forward voltage	$I_F = 10 \text{ mA}$	V_F	1.1	1.4	1.7	V
Reverse current	$V_R = 5 \text{ V}$	I_R		0.01	10	μA
Input capacitance	$f = 1 \text{ MHz}, V_F = 0 \text{ V}$	C_I		38		pF
OUTPUT						
High level supply current	$V_E = 0.5 \text{ V}, I_F = 0 \text{ mA}$	I_{CCH}		4.3	10	mA
	$V_E = V_{CC}, I_F = 0 \text{ mA}$	I_{CCH}		3.3		mA
Low level supply current	$V_E = 0.5 \text{ V}, I_F = 10 \text{ mA}$	I_{CCL}		4.3	13	mA
	$V_E = V_{CC}, I_F = 10 \text{ mA}$	I_{CCL}		3.3	6	mA
High level output current	$V_E = 2 \text{ V}, V_O = 5.5 \text{ V}, I_F = 250 \mu\text{A}$	I_{OH}		0.02	10	μA
Low level output voltage	$V_E = 2 \text{ V}, I_F = 5 \text{ mA}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	V_{OL}		0.2	0.6	V
Input threshold current	$V_E = 2 \text{ V}, V_O = 0.6 \text{ V}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	I_{TH}		2.4	5	mA
Input-output capacitance	$f = 1 \text{ MHz}, T_{amb} = 25 \text{ }^\circ\text{C}$	C_{IO}		0.9		pF
High level enable current	$V_E = 2 \text{ V}$	I_{EH}		-0.6	-1.6	mA
Low level enable current	$V_E = 0.5 \text{ V}$	I_{EL}		-0.8	-1.6	mA
High level enable voltage		V_{EH}	2			V
Low level enable voltage		V_{EL}			0.8	V

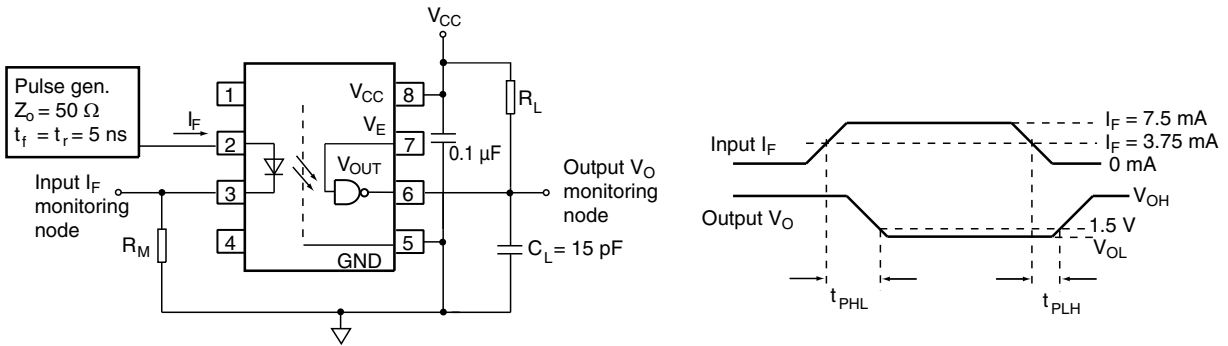
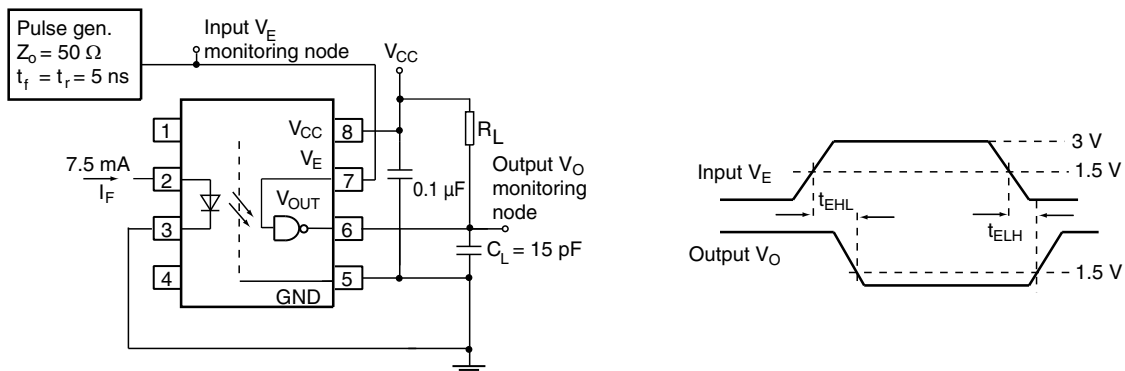
Notes

- Over recommended temperature ($T_{amb} = -40 \text{ }^\circ\text{C}$ to $+100 \text{ }^\circ\text{C}$), $V_{CC} = 5 \text{ V}$, $I_F = 7.5 \text{ mA}$ unless otherwise specified. All typicals at $T_{amb} = 25 \text{ }^\circ\text{C}$, $V_{CC} = 5 \text{ V}$.
- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

SWITCHING CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to high output level	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	t_{PLH}	20	49	100	ns
Propagation delay time to low output level	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	t_{PHL}	25	46	100	ns
Pulse width distortion	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	$ t_{PHL} - t_{PLH} $		3.1	40	ns
Propagation delay skew	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	t_{PSK}		16	40	ns
Output rise time (10 % to 90 %)	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	t_r		14		ns
Output fall time (90 % to 10 %)	$R_L = 350 \Omega, C_L = 15 \text{ pF}$	t_f		7		ns
Propagation delay time of enable from V_{EH} to V_{EL}	$R_L = 350 \Omega, C_L = 15 \text{ pF}, V_{EL} = 0 \text{ V}, V_{EH} = 3 \text{ V}$	t_{ELH}		11		ns
Propagation delay time of enable from V_{EL} to V_{EH}	$R_L = 350 \Omega, C_L = 15 \text{ pF}, V_{EL} = 0 \text{ V}, V_{EH} = 3 \text{ V}$	t_{EHL}		9		ns

Notes

- Over recommended temperature ($T_{amb} = -40 \text{ }^\circ\text{C}$ to $+100 \text{ }^\circ\text{C}$), $V_{CC} = 5 \text{ V}$, $I_F = 7.5 \text{ mA}$ unless otherwise specified. All typicals at $T_{amb} = 25 \text{ }^\circ\text{C}$, $V_{CC} = 5 \text{ V}$.
- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.


 Fig. 2 - Test Circuit for t_{PLH} , t_{PHL} , t_r and t_f

 Fig. 3 - Test Circuit for t_{EHL} and t_{ELH}

COMMON MODE TRANSIENT IMMUNITY							
PARAMETER	TEST CONDITION	DEVICE	SYMBOL	MIN.	TYP.	MAX.	UNIT
Common mode transient immunity	$ V_{CM} = 1 \text{ kV}$, $V_{CC} = 5 \text{ V}$, $I_F = 0 \text{ mA}$ (1)(2)(3)(4)	VOW137	$ CM_H $	10 000			$\text{V}/\mu\text{s}$
	$ V_{CM} = 1 \text{ kV}$, $V_{CC} = 5 \text{ V}$, $I_F = 0 \text{ mA}$ (1)(2)(5)	VOW2611	$ CM_H $	25 000	40 000		$\text{V}/\mu\text{s}$
	$ V_{CM} = 1 \text{ kV}$, $V_{CC} = 5 \text{ V}$, $I_F = 7.5 \text{ mA}$ (1)(2)(3)(4)	VOW137	$ CM_L $	10 000			$\text{V}/\mu\text{s}$
	$ V_{CM} = 1 \text{ kV}$, $V_{CC} = 5 \text{ V}$, $I_F = 7.5 \text{ mA}$ (1)(2)(5)	VOW2611	$ CM_L $	25 000	40 000		$\text{V}/\mu\text{s}$

Notes

- Over recommended temperature ($T_{amb} = -40 \text{ }^\circ\text{C}$ to $+100 \text{ }^\circ\text{C}$), $V_{CC} = 5 \text{ V}$, $I_F = 7.5 \text{ mA}$ unless otherwise specified. All typicals at $T_{amb} = 25 \text{ }^\circ\text{C}$, $V_{CC} = 5 \text{ V}$.
- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.
- With pulling V_E to logic high state will improve the CMR performance.
- VOW137 CMTI test circuit refer to figure 4.
- VOW2611 CMTI test circuit refer to figure 5.

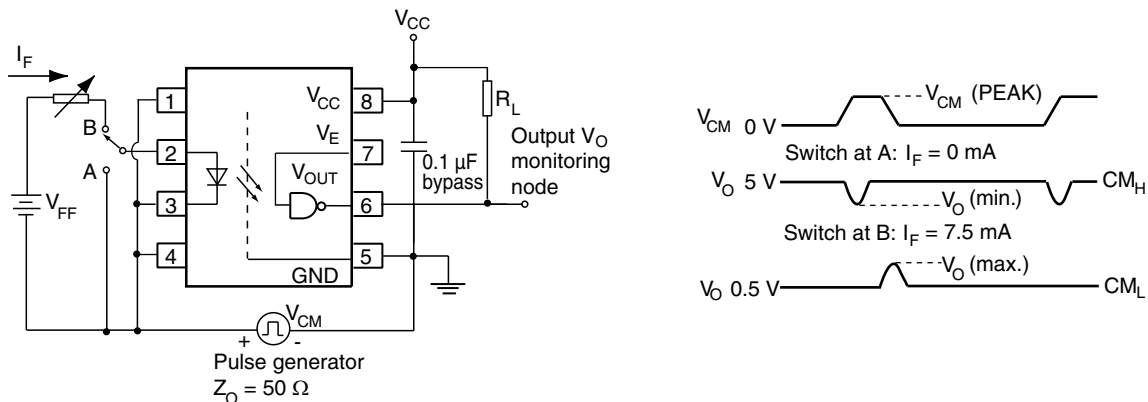


Fig. 4 - VOW137 Test Circuit for Common Mode Transient Immunity

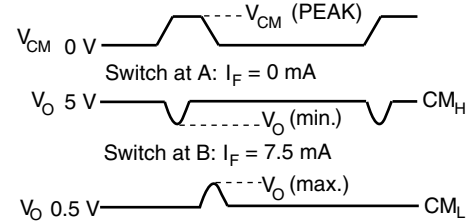
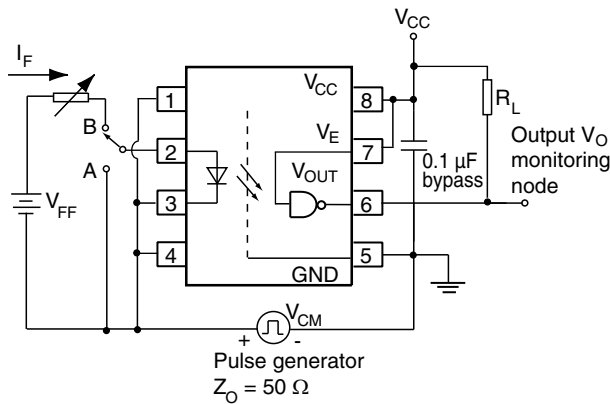


Fig. 5 - VOW2611 Test Circuit for Common Mode Transient Immunity

SAFETY AND INSULATION RATINGS					
PARAMETER		SYMBOL	VALUE	UNIT	
MAXIMUM SAFETY RATINGS					
Output safety power		P_{SO}	700	mW	
Input safety current		I_{SI}	350	mA	
Safety temperature		T_S	150	°C	
Comparative tracking index		CTI	250		
INSULATION RATED PARAMETERS					
Maximum withstanding isolation voltage		$t = 1 \text{ min}$	V_{ISO}	5300	V_{RMS}
Maximum transient isolation voltage			V_{IOTM}	8000	V_{peak}
Maximum repetitive peak isolation voltage			V_{IORM}	1414	V_{peak}
Insulation resistance		$T_{amb} = 25 \text{ °C}, V_{DC} = 500 \text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
Isolation resistance		$T_{amb} = 100 \text{ °C}, V_{DC} = 500 \text{ V}$	R_{IO}	$\geq 10^{11}$	Ω
Input to output test voltage, method b		$V_{IORM} \times 1.875 = V_{PR}$, 100 % production test with $t_M = 1 \text{ s}$, partial discharge $< 5 \text{ pC}$	V_{PR}	2651	V_{peak}
Input to output test voltage, method a		$V_{IORM} \times 1.6 = V_{PR}$, 100 % production test with $t_M = 10 \text{ s}$, partial discharge $< 5 \text{ pC}$	V_{PR}	2262	V_{peak}
Climatic classification (according to IEC 68 part 1)				55/100/21	
Environment (pollution degree in accordance to DIN VDE 0109)				2	
Clearance distance (DIP-8, widebody)				≥ 10	mm
Creepage distance (DIP-8, widebody)				≥ 10	mm
Insulation thickness			DTI	≥ 0.4	mm

Note

- As per IEC 60747-5-5, §7.4.3.8.1, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

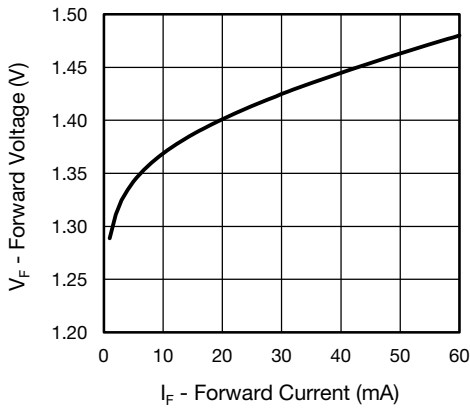


Fig. 6 - Forward Voltage vs. Forward Current

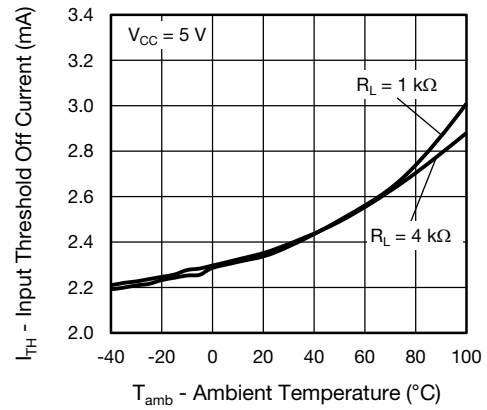


Fig. 9 - Input Threshold Off Current vs. Ambient Temperature

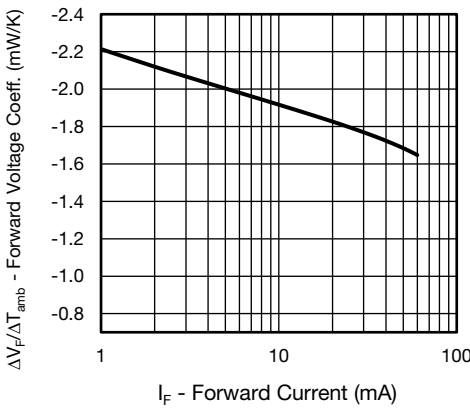


Fig. 7 - Forward Voltage Coefficient vs. Forward Current

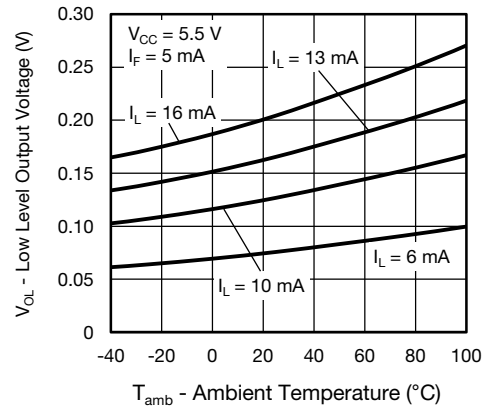


Fig. 10 - Low Level Output Voltage vs. Ambient Temperature

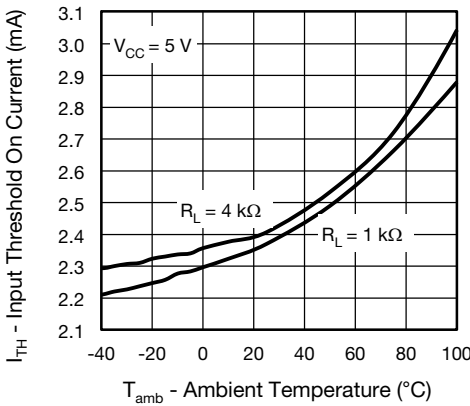


Fig. 8 - Input Threshold On Current vs. Ambient Temperature

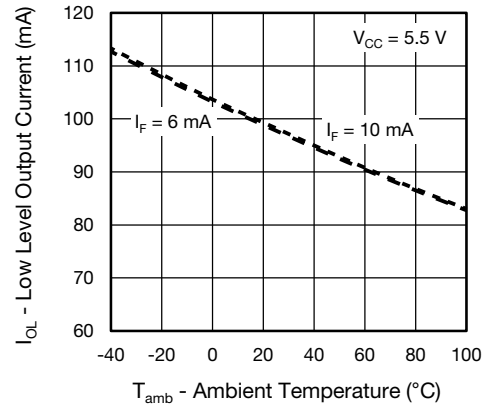


Fig. 11 - Low Level Output Current vs. Ambient Temperature

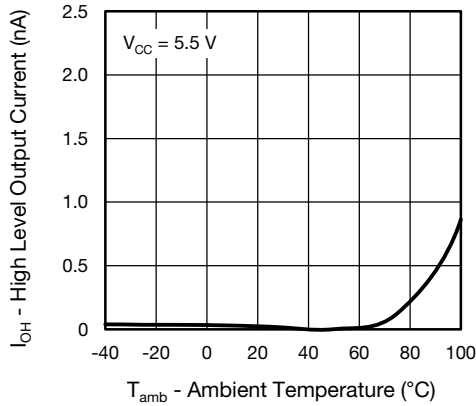


Fig. 12 - High Level Output Current vs. Ambient Temperature

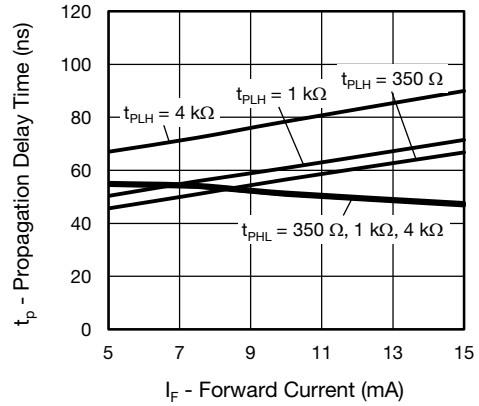


Fig. 15 - Propagation Delay vs. Forward Current

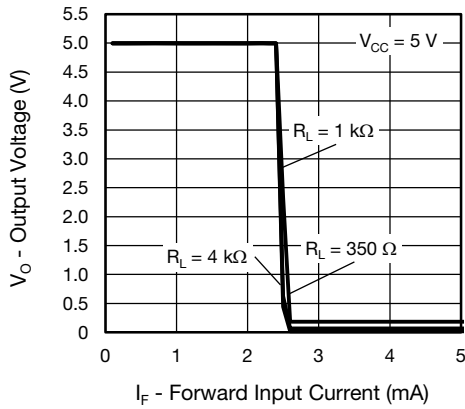


Fig. 13 - Output Voltage vs. Forward Current

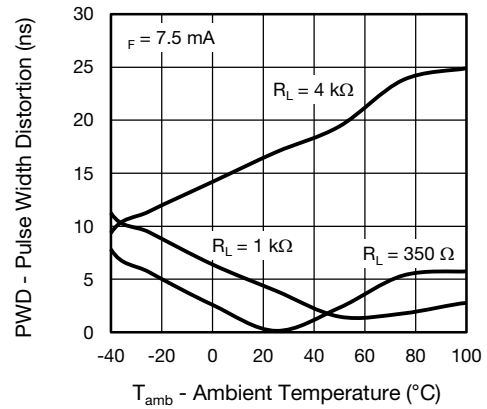


Fig. 16 - Pulse Width Distortion vs. Ambient Temperature

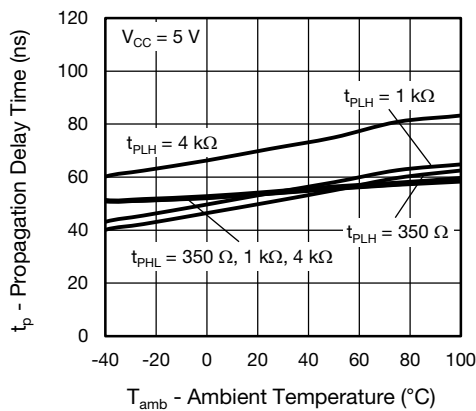


Fig. 14 - Propagation Delay vs. Ambient Temperature

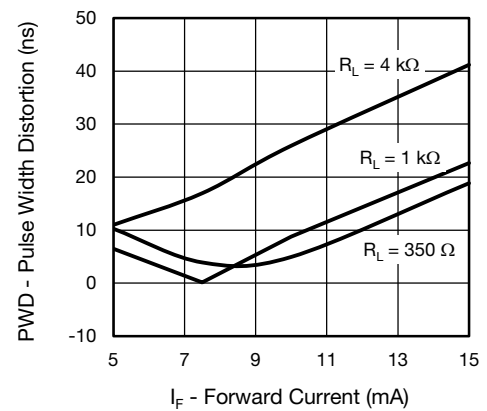


Fig. 17 - Pulse Width Distortion vs. Forward Current

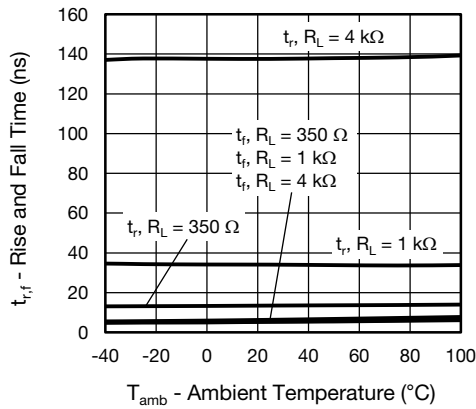


Fig. 18 - Rise and Fall Time vs. Ambient Temperature

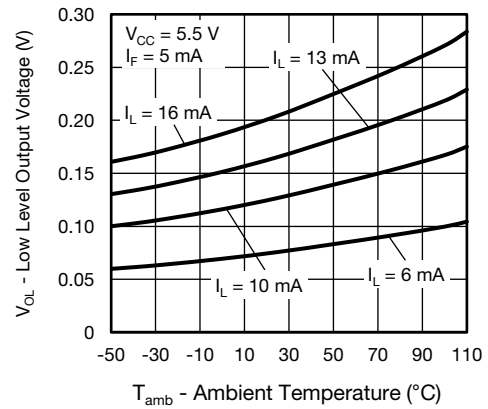


Fig. 21 - Low Level Output Voltage vs. Ambient Temperature

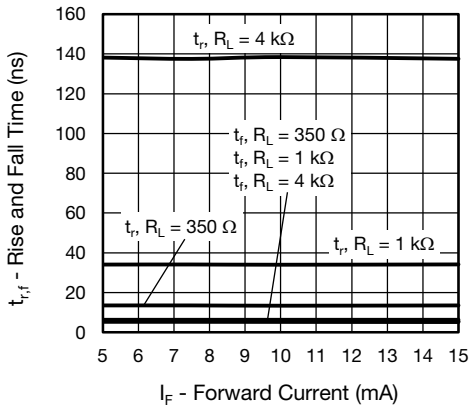


Fig. 19 - Rise and Fall Time vs. Forward Current

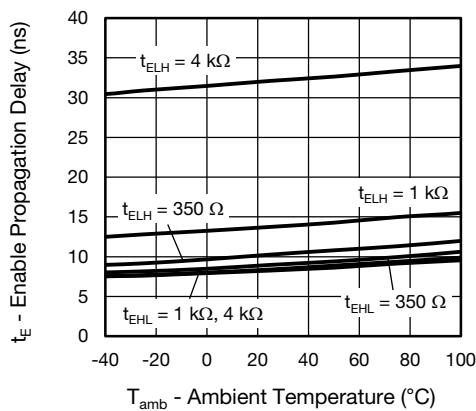
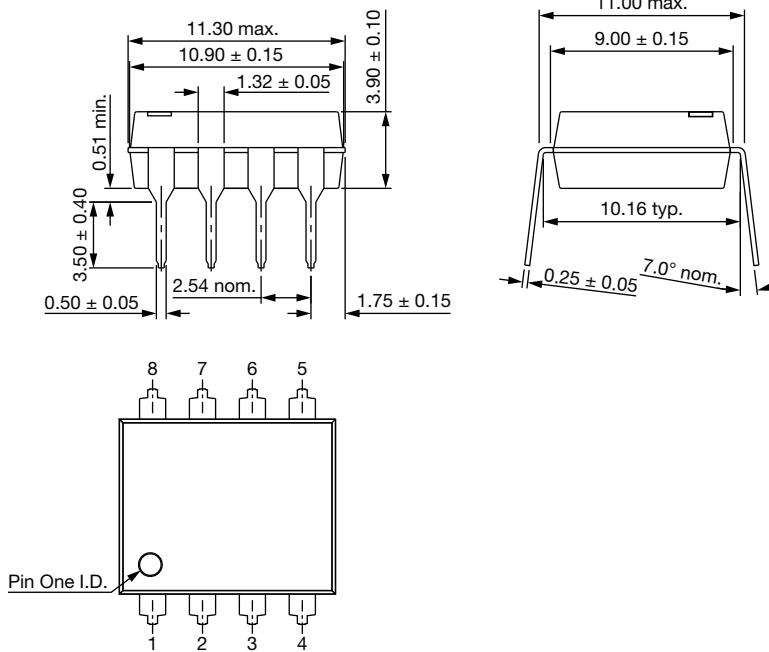


Fig. 20 - Enable Propagation Delay vs. Ambient Temperature

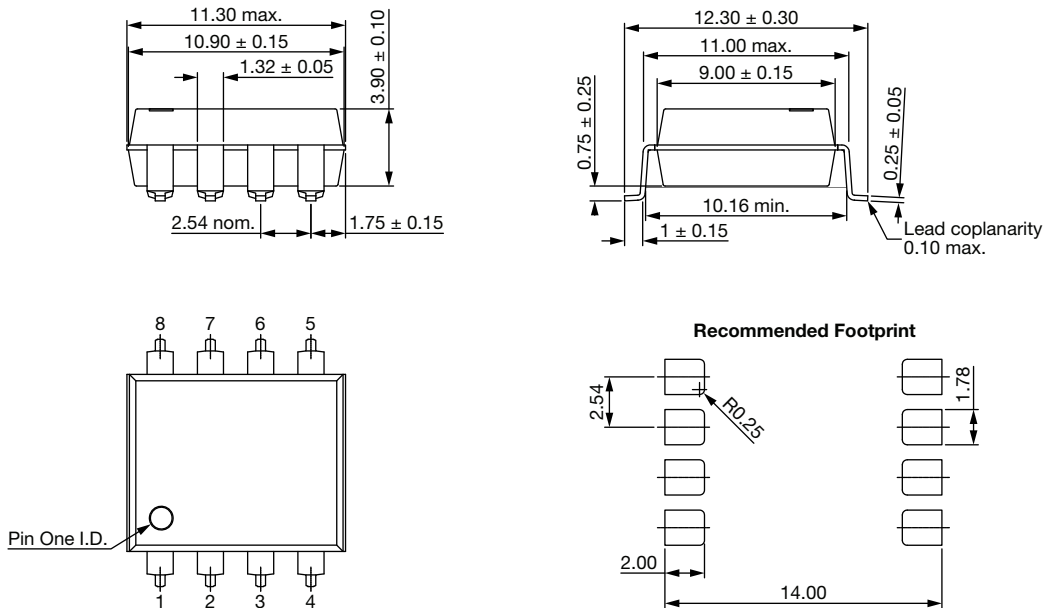


PACKAGE DIMENSIONS in millimeters

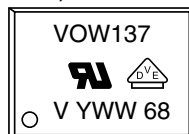
DIP-8, widebody



SMD-8, widebody, (Option 7)



PACKAGE MARKING (Example of VOW137-X017T)



Note

- Tape and reel suffix (T) is not part of the package marking.

PACKING INFORMATION (Tape and Reel)

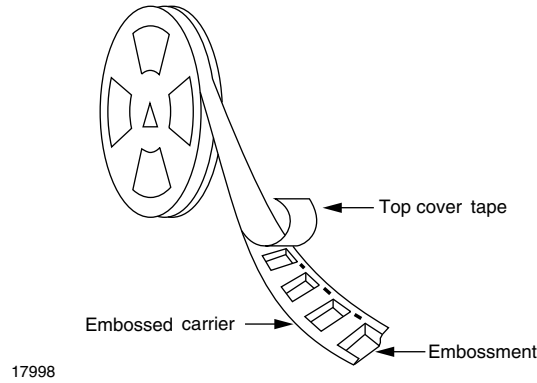
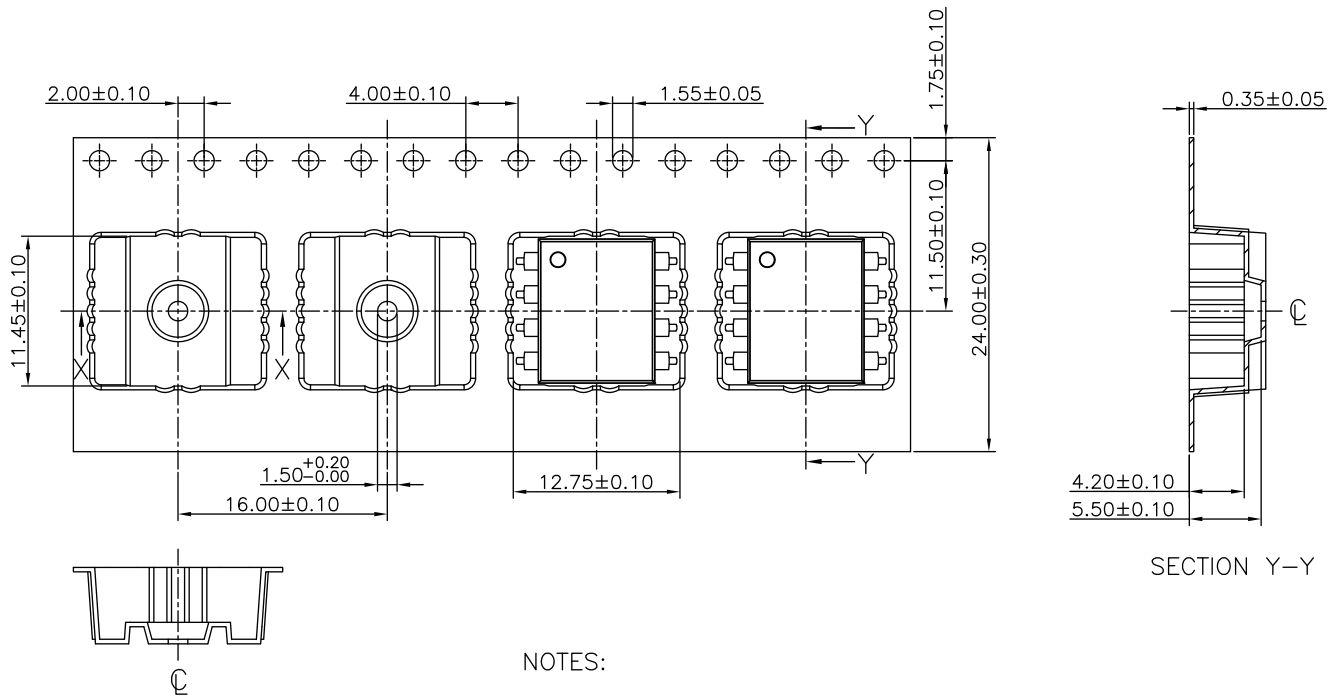


Fig. 22 - Tape and Reel Shipping Medium



NOTES:

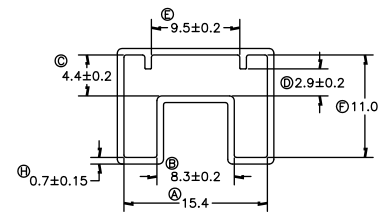
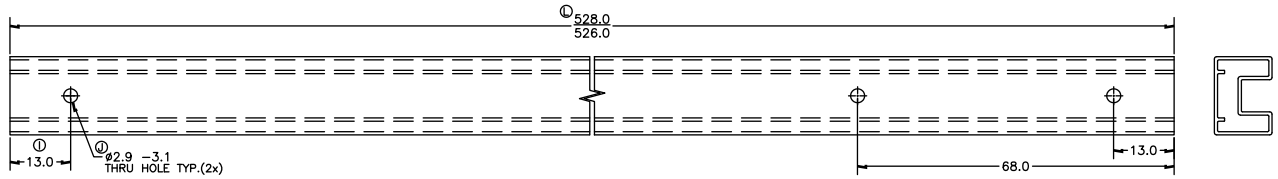
- 1) CUMULATIVE TOLERANCE OF 10 SPROCKET HOLES IS ± 0.20 .

Fig. 23 - Tape and Reel Packing Option 7 (750 parts per reel)



PACKING INFORMATION (Tubes)

DEVICE PER TUBE			
TYPE	UNITS/TUBE	TUBE/BOX	UNITS/BOX
DIP-8, widebody	40	30	1200



TUBE COLOUR:	CLEAR
PRINT COLOUR:	-

1. ALL DIMENSIONS ARE IN MILLIMETERS, U.O.S.

1. ALL TUBE TOLERANCES TO BE ± 0.25 UNLESS OTHERWISE SPECIFIED.
2. ALL RADII AND ANGLES REFERENCE ONLY, UNLESS OTHERWISE SPECIFIED.



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